



Gp 2809 #2

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Vassoudevane LEBONHEUR ET AL.

Serial No.: 09/964,709

Filing Date: September 28, 2001

For: METHOD OF IMPROVING THERMAL PERFORMANCE IN
FLIP CHIP/INTEGRAL HEAT SPREADER PACKAGES USING
LOW MODULUS THERMAL INTERFACE MATERIAL

LETTER SUBMITTING FORMAL DRAWINGS

Assistant Commissioner for Patents
Washington, D.C. 20231

November 6, 2001

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Sir:

Submitted herewith are four (4) sheets of formal drawings illustrating Figs.

1-5 in connection with the above-identified application.

Respectfully submitted,

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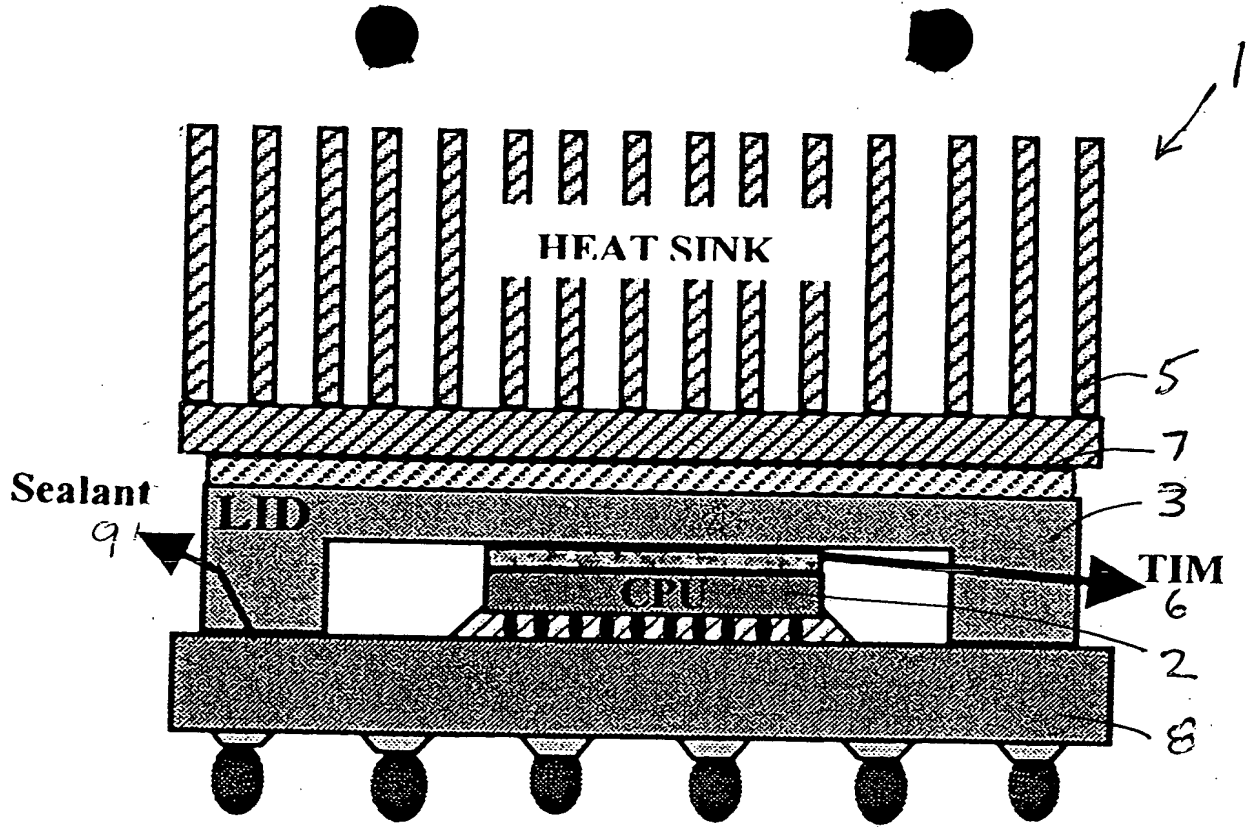


FIG. 1

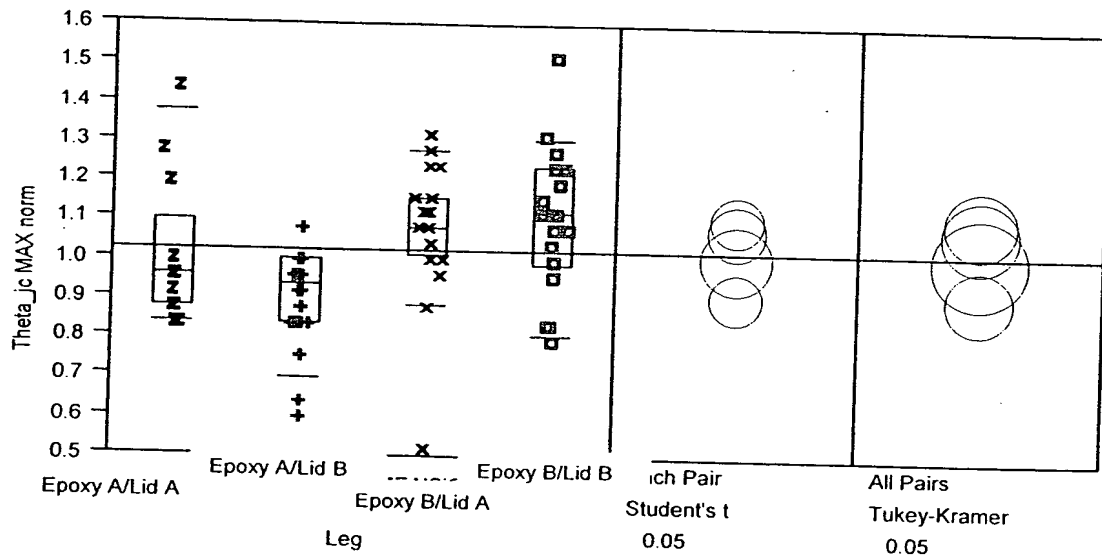


FIG. 2

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FIG. 3

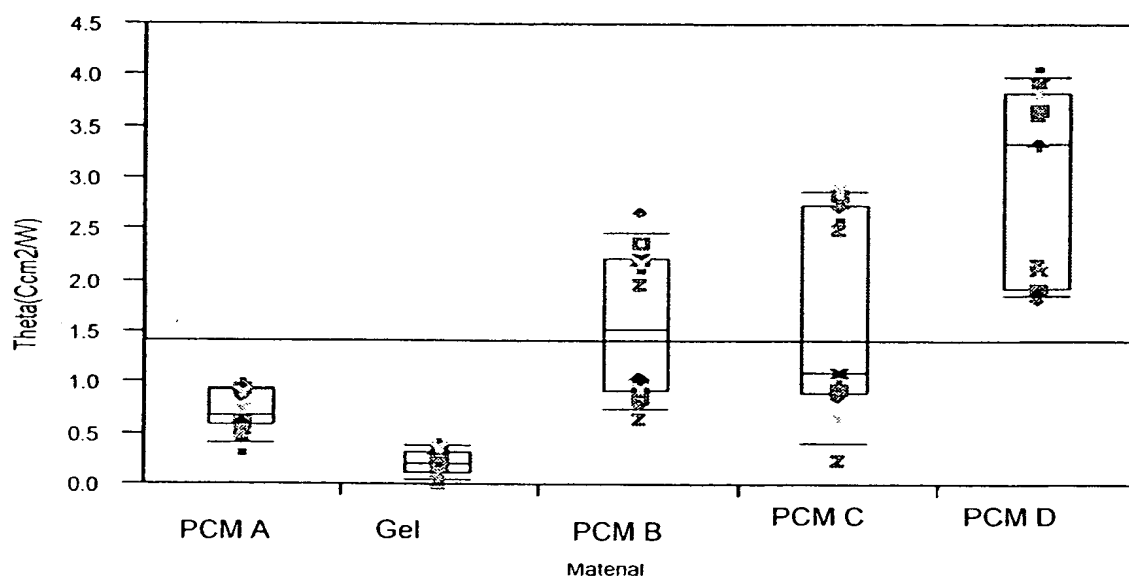
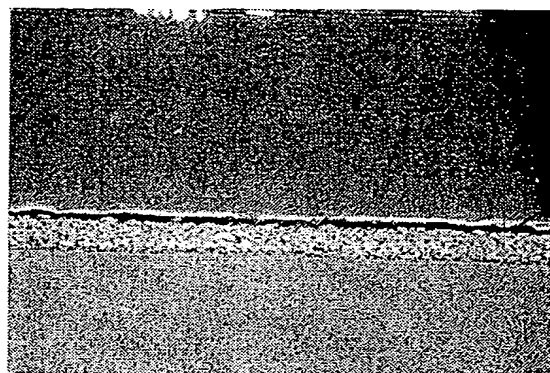


FIG. 4

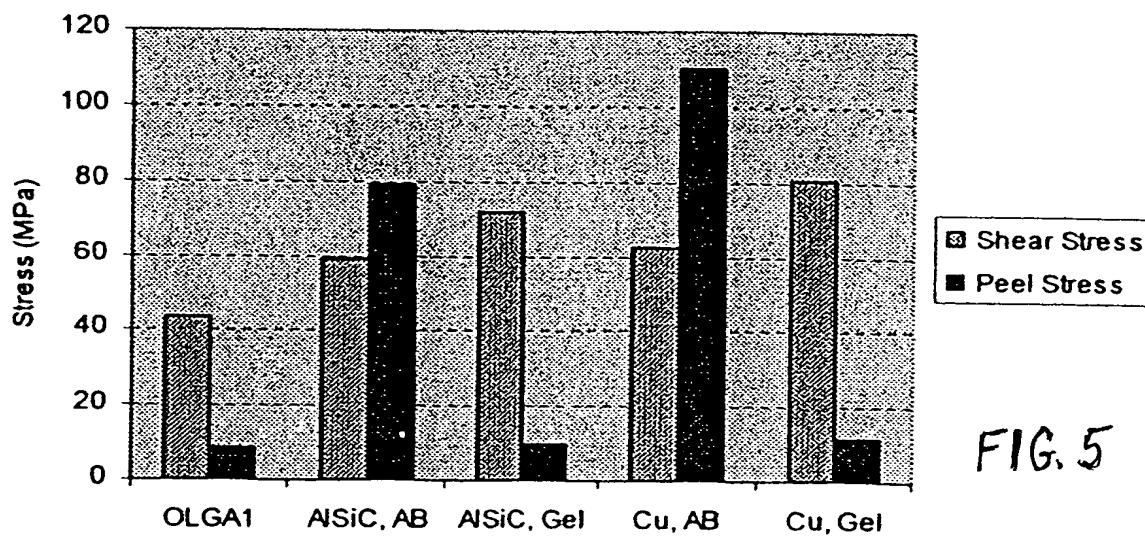


FIG. 5

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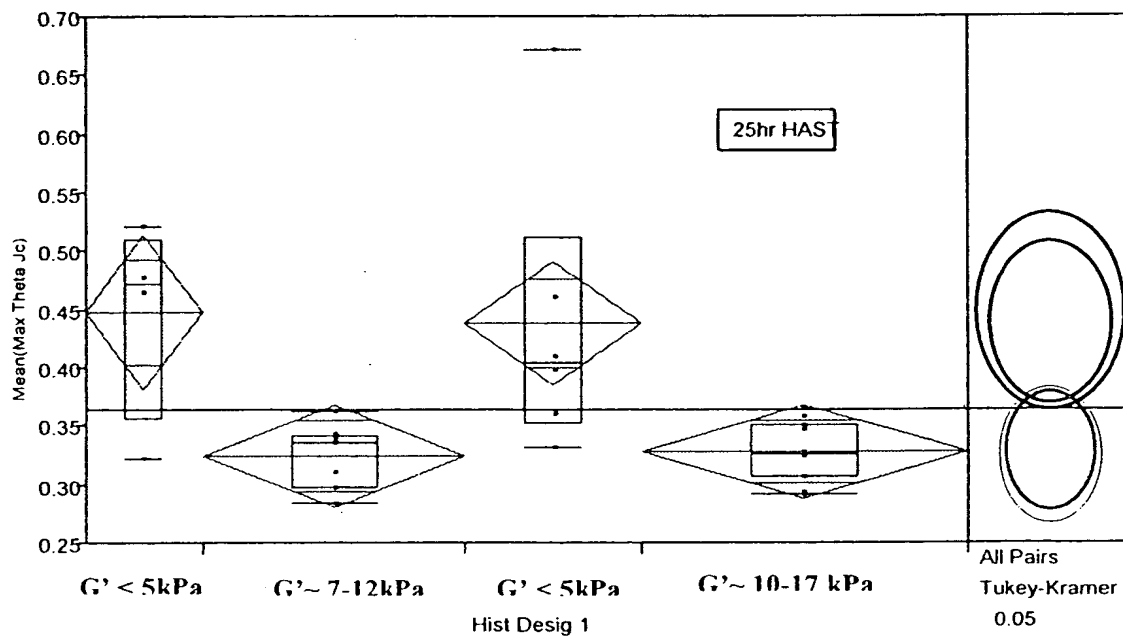
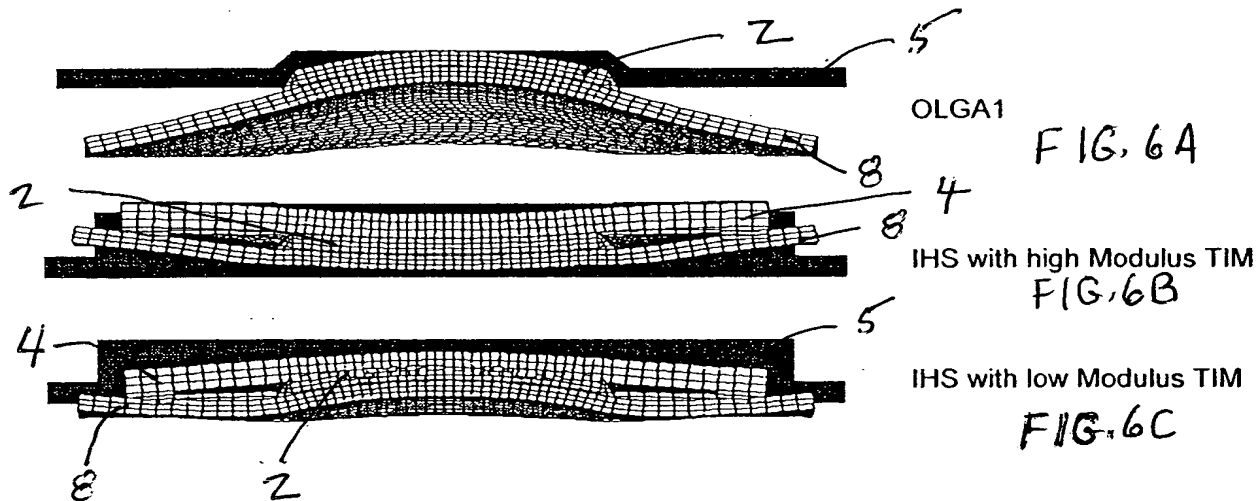


FIG. 7